

规格书编号

SPEC NO: HDR378.9MS6SP01

PRODUCT 产品:

产品规格书(预期) Preliminary SPECIFICATION

SAW RESONATOR

CUSTOMER 客 户:_____

-						
MODEL NO 型 号:	HDR378.9M-S6					
PREPARED 编 制:	CHECKED 审 核	₹:				
APPROVED 批准:	DATE日期]: 2018-9-10				
客户确认 CUSTOMER RECEIVED:						
审核 CHECKE	D 批准 APPROVED	日期 DATE				

无锡市好达电子有限公司 Shoulder Electronics Limited



更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

1. Scope

This specification shall cover the characteristics of 1-port SAW resonator with R378.9M used for remote-control security.

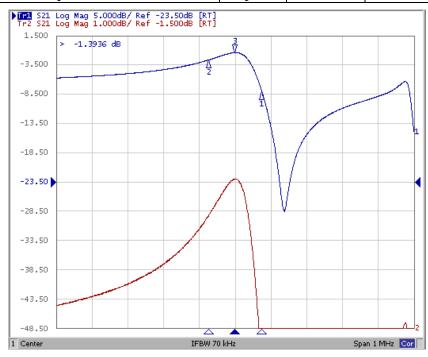
2. Electrical Specification

2.1 Maximum Rating

DC Voltage VDC	10V
AC Voltage Vpp	10V 50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
Max input Power	10dBm

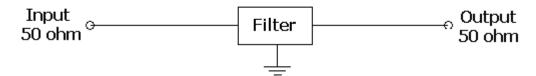
2.2 Electronic Characteristics

Item		Unites	Minimum	Typical	Maximum	
Center Frequency		MHz	378.825	378.900	378.975	
Insertion Loss		dB		1.5	2.5	
Quality Factor		Unload Q		8000	12000	
		50Ω Loaded Q		800	2000	
Temperature	Turnover Temperature		$^{\circ}\!\mathbb{C}$	10	25	40
Stability	Freq.temp.Coefficient		ppm/℃		0.032	
Frequency Aging		ppm/yr		<±10		
DC. Insulation Resistance		ΜΩ	1.0			
Transducer Static Capacitance C0		pF		2.3		

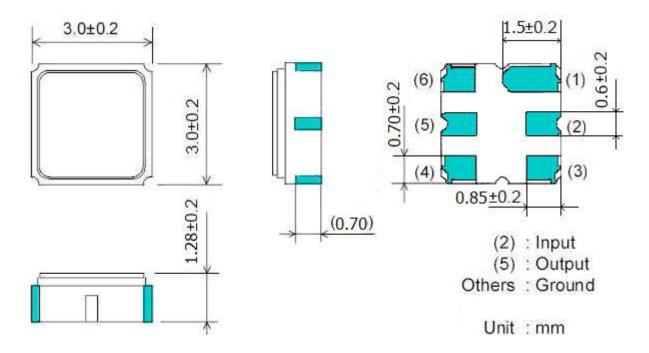




3. Test Circuit



4. Dimension



5. Environment Characteristic

5-1 High temperature exposure

Subject the device to $+85^{\circ}$ C for 16 hours. Then release the resonator into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-3 Temperature cycling

Subject the device to a low temperature of -40° C for 30 minutes. Following by a high temperature of $+85^{\circ}$ C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260° C $\pm 10^{\circ}$ C for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

5-5 Solderability

Subject the device terminals into the solder bath at 245°C ± 5 °C for 5s, More than 95%



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area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

6. Remark

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.